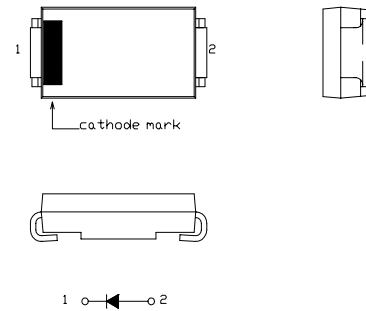


# SBD Type : NSQ03A06

## FEATURES

- \* **FLAT-PAK** Surface Mounting Device
- \* Low Forward Voltage Drop
- \* Low Power Loss, High Efficiency
- \* High Surge Capability
- \* 30 Volts through 60Volts Types Available
- \* Packaged in 16mm Tape and Reel
- \* Not Rolling During Assembly

## OUTLINE DRAWING



## Maximum Ratings

Approx Net Weight:0.16g

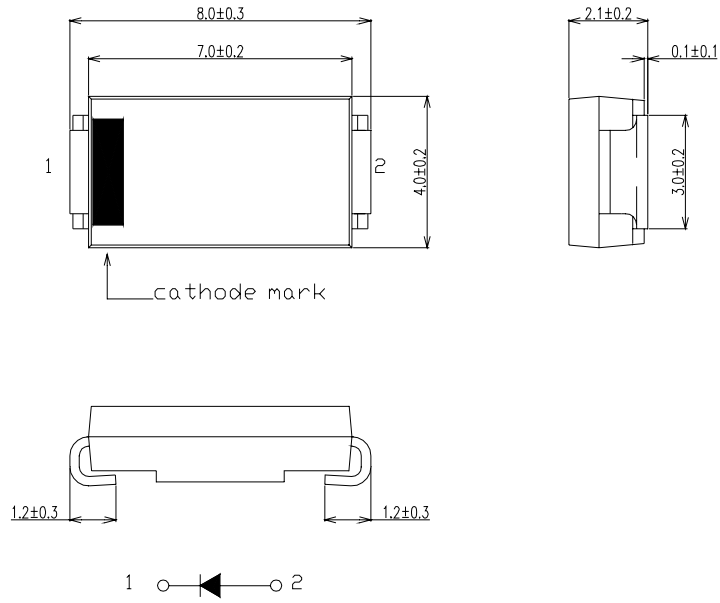
Rating	Symbol	NSQ03A06		Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	60		V
Average Rectified Output Current	$I_o$	1.36	$T_a=25^{\circ}C$ *1	50Hz Half Sine Wave Resistive Load
		3.0	$T_l=96^{\circ}C$	
RMS Forward Current	$I_{F(RMS)}$	4.71		A
Surge Forward Current	$I_{FSM}$	50	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	$T_{jw}$	-40 to +150		$^{\circ}C$
Storage Temperature Range	$T_{stg}$	-40 to +150		$^{\circ}C$

## Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	$I_{RM}$	$T_j = 25^{\circ}C, V_{RM} = V_{RRM}$	-	-	3	mA
Peak Forward Voltage	$V_{FM}$	$T_j = 25^{\circ}C, I_{FM} = 3.0A$	-	-	0.58	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$ Alumina Substrate Mounted *1	-	-	89	$^{\circ}C/W$
	Junction to Lead	$R_{th(j-l)}$ -	-	-	13	

\*1 Alumina Substrate Mounted (Soldering Lands=2x3.5mm, Both Sides)  
( $T_l$ : Lead Temperature)

NSQ03A06 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

